



Full Material Declaration for attached parts list

Report generated: 22 May 2025, 13:30 GMT



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Declarations authorised by
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Declaration effective from: 01 January 2010 [Approved: 22 May 2025 13:13 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.4%	Nickel REACH Article 67 Exemption	7440-02-0	0.95%
			Gold	7440-57-5	10.95%
			Polydimethylsiloxane rubber	63394-02-5	25.2%
			Silicon	7440-21-3	62.9%
			Silver	7440-22-4	1.5%
			Tin	7440-31-5	5.297%
Die attach	Lead and Lead alloys	0.2%	Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	93.203%
			Carbon black	1333-86-4	0.5%
			Aluminum hydroxide (Al(OH)3)	21645-51-2	1.5%
			Phenol, polymer with formaldehyde	9003-35-4	8%
Encapsulation	EP (Epoxy resin)	44.9%	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	20%
			Silicon dioxide Exempt from other regulatory requirements	14808-60-7	70%
Leadfinish	Tin plating	2.2%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	52.3%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name
D 8x7.5 (DCN) HF	Diode axial